

PATENT ABSTRACTS OF JAPAN

(11)Publication number : 2002-100870

(43)Date of publication of application : 05.04.2002

(51)Int.Cl.

H05K 3/46
H01G 2/06
H01G 4/38
H01G 4/40
H05K 1/18

(21)Application number : 2000-266282

(71)Applicant : IBIDEN CO LTD

(22)Date of filing : 01.09.2000

(72)Inventor : INAGAKI YASUSHI
ASAHI MOTOO
O TOUTO
YAHASHI HIDEO
SHIRAI SEIJI

(30)Priority

Priority number : 11248311

Priority date : 02.09.1999

Priority country : JP

11369003

27.12.1999

2000221350

21.07.2000

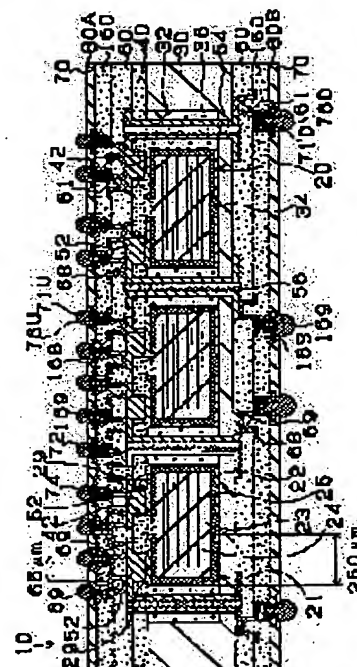
JP

JP

(54) PRINTED WIRING BOARD AND MANUFACTURING METHOD THEREOF

(57)Abstract:

PROBLEM TO BE SOLVED: To provide a printed wiring board together with its manufacturing method which incorporates capacitors for raised connection reliability.
SOLUTION: A core substrate 30 incorporates chip capacitors 20, and relatively large vias 52 which connect terminals 21 and 22 of the chip capacitors 20 is formed on the chip capacitors 20. A plurality of relatively small vias 69 connected to the vias 52 are arranged at an inner-layer resin insulating layer 60 on the upper surface of the core substrate 30. Thus, the terminals 21 and 22 of the capacitors 20 are surely connected to the vias 52 by coping with displacement of the capacitors 20.



LEGAL STATUS

[Date of request for examination]

[Date of sending the examiner's decision of rejection]

[Kind of final disposal of application other than the examiner's decision of rejection or application converted registration]

[Date of final disposal for application]

[Patent number]

[Date of registration]

[Number of appeal against examiner's decision of rejection]

[Date of requesting appeal against examiner's decision of rejection]

[Date of extinction of right]

Copyright (C); 1998,2003 Japan Patent Office